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(54) Title: HYBRID MATERIAL FOR OPTOELECTRONIC APPLICATIONS

(57) Abstract: A hybrid material for light emitting diodes, comprising a) an organopolysilazane material, comprising repeating units of formulae (I) $[-SiR^1R^2 - NR^3-]_x$ and (II) $[-SiHR^4 - NR^5-]_y$, wherein the symbols and indices have the following meanings: R^1 is C_2-C_6 -alkenyl or C_4-C_6 -alkadienyl; R^2 is H or an organic group; R^3 is H or an organic group; R^4 is H or an organic group; R^5 is H or an organic group; x is 0.001 to 0.2; and y is 2x to (1 - x), with the proviso that $x+y \leq 1$ and that y can be 0 if R^2 is H, and b) inorganic nanoparticles having a mean diameter in the range of from 1 to 30 nm, which are surface modified with a capping agent comprising a C_1-C_{18} -alkyl and/or C_1-C_{18} -alkenyl group, is useful as encapsulation material for LEDs.

